



Material Content Data Sheet



Sales Product Name	TLE4998S8D			Issued	1. August 2018			
MA#	MA002020032							
Package	PG-TDSO-8-2			Weight*	67.99 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.851	5.66	5.66	56650	56650
leadframe	non noble metal	zinc	7440-66-6	0.064	0.09		947	
	non noble metal	tin	7440-31-5	0.080	0.12		1183	
	non noble metal	chromium	7440-47-3	0.097	0.14		1420	
wire	non noble metal	copper	7440-50-8	31.938	46.99	47.34	469768	473318
	noble metal	gold	7440-57-5	0.118	0.17	0.17	1736	1736
	encapsulation	organic material	carbon black	1333-86-4	0.060	0.09		885
leadfinish	plastics	epoxy resin	-	3.248	4.78		47772	
	inorganic material	silicondioxide	60676-86-0	26.765	39.37	44.24	393675	442332
	non noble metal	tin	7440-31-5	0.497	0.73	0.73	7313	7313
plating	noble metal	silver	7440-22-4	0.778	1.14	1.14	11442	11442
glue	plastics	epoxy resin	-	0.123	0.18		1802	
	plastics	acrylic resin	-	0.123	0.18		1802	
	inorganic material	silicondioxide	60676-86-0	0.245	0.36	0.72	3605	7209
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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